



Integrated Device Technology, Inc.  
6024 Silver Creek Valley Road, San Jose, CA - 95138

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1903-01**                      Date:    March 28, 2019  
 Product Affected:    4RCD0124KC0ATG  
                                  4RCD0124KC0ATG8  
                                  4RCD0124KC0ATG8/B  
                                  4RCD0124KC0ATG8/M  
                                  4RCD0124KC0ATGI  
                                  4RCD0124KC0ATGI8  
 Date Effective:    June 28, 2019

MEANS OF DISTINGUISHING CHANGED DEVICES:  
 Product Mark  
 Back Mark                      Lot # will have a "D" prefix  
 Date Code  
 Date Code  
 Other

Contact:            IDT PCN DESK

Attachment:        Yes                       No

E-mail:             [pcndesk@idt.com](mailto:pcndesk@idt.com)

Samples:            Please contact your local sales representative for sample request & availability.

**DESCRIPTION AND PURPOSE OF CHANGE:**

- Die Technology
- Wafer Fabrication Process
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site
- Data Sheet
- Other

This notification is to advise our customers that IDT is adding Amkor Korea as an alternate bump location on the above products. In addition, the assembly location will also be transferred from Amkor Philippines to Amkor Korea as a result of Amkor Philippines discontinuing the assembly processes of these products.

Amkor Korea is currently a qualified IDT Subcontractor.

There is no change to the moisture performance rating.

Please refer to Attachment 1 for the qualification summary and material set details.

**RELIABILITY/QUALIFICATION SUMMARY:**

Qualification has been successfully completed. There is no change in MSL rating.

**CUSTOMER ACKNOWLEDGMENT OF RECEIPT:**

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: \_\_\_\_\_

*Approval for shipments prior to effective date.*

Name/Date: \_\_\_\_\_

E-Mail Address: \_\_\_\_\_

Title: \_\_\_\_\_

Phone# /Fax# : \_\_\_\_\_

**CUSTOMER COMMENTS:**

\_\_\_\_\_  
 \_\_\_\_\_  
 \_\_\_\_\_

**IDT ACKNOWLEDGMENT OF RECEIPT:**

RECD. BY: \_\_\_\_\_

DATE \_\_\_\_\_



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## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT 1 - PCN # : A1903-01

**PCN Type:** Add alternate Bump Location & Change Assembly Location & Assembly Material Sets

**Data Sheet Change:** N/A

#### Detail Of Change:

This notification is to advise our customers that IDT is adding Amkor Korea as an alternate bump location on the above products. In addition, the assembly location will also be transferred from Amkor Philippines to Amkor Korea as a result of Amkor Philippines discontinuing the assembly processes of these products.

Amkor Korea is currently a qualified IDT Subcontractor.

There is no change in form, fit and function of the products including RoHS compliance and MSL rating.

IDT requests customers to respond to this notice within 30 days, with an indication if samples will be required. Samples must be placed within 30 days if required for qualification and approval to avoid any disruption in supply.

#### FCCSP-48: Qualified Material Sets, by Assembly Subcontractor

	Existing	New
Die Bump Location	ATT - Amkor, Taiwan	ATT - Amkor, Taiwan ATK - Amkor, Korea
Material Set / Assembly	ATP - Amkor, Philippines	ATK - Amkor, Korea
Die Bump	Sn1.8Ag	Sn1.8Ag
Underfill Material	MUF-1	MUF-32
Substrate	AUS703-140PS 4L	AUS703-140PS 4L
Solder Balls	Sn96.5/Ag3.0/Cu0.5	Sn96.5/Ag3.0/Cu0.5



## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT 1 - PCN # : A1903-01

#### Qualification Information and Qualification Data:

**Affected Packages:** FCCSP-253

**Assembly Material:** The affected package type is using the respective subcon standard materials as shown on page 1 of this attachment. Qualification testing was completed on the worse case package.

**Qual Plan & Results:** Tests are in accordance with JEDEC47 recommended tests

**Qualification Vehicle: FCCSP-253** (3 lots)

Test Description	Test Method	Test Results (Rej/SS)		
		Lot 1	Lot 2	Lot 3
<sup>1</sup> HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0 / 25	0 / 25	0 / 25
<sup>1</sup> HAST - unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	0 / 25	0 / 25	0 / 25
<sup>1</sup> Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0 / 25	0 / 25	0 / 25
High Temperature Storage Test (150°C, 1000 hours)	JESD22-A103	0 / 25	0 / 25	0 / 25
Moisture Sensitivity Level, MSL	J-STD-020C	0 / 25	0 / 25	-

Notes: 1. HAST and Temperature Cycle were subjected to Preconditioning per JESD22-A113 for MSL 3.